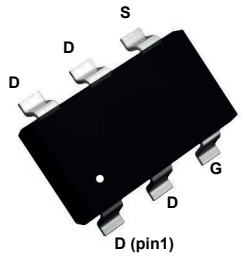
GSFR4099

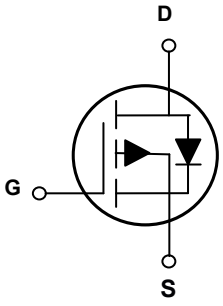
40V P-Channel MOSFET

Main Product Characteristics

BV_{DSS}	-40V
$R_{DS(ON)}$	105mΩ (Max.)
I_D	-3.5A



SOT-23-6L



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery

Description

The GSFR4099 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-40	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous (T_A=25°C)	I_D	-3.5	A
Drain Current-Continuous (T_A=70°C)		-2.7	
Drain Current-Pulsed[1]	I_{DM}	-16	A
Power Dissipation (T_A=25°C)	P_D	2.1	W
Power Dissipation-Derate above 25°C		0.0168	W/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	60	°C/W
Operating Junction Temperature Range	T_J	-55 To +150	°C
Storage Temperature Range	T_{STG}	-55 To +150	°C

Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_D=-250uA	-40	-	-	V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=-40V, V_{GS}=0V, T_J=25°C	-	-	-1	μA
		V_{DS}=-32V, V_{GS}=0V, T_J=125°C	-	-	-10	μA
Gate-Source Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}=-10V, I_D=-2A	-	88	105	mΩ
		V_{GS}=-4.5V, I_D=-1.5A	-	128	166	
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS}, I_D=-250uA	-1.2	-1.8	-2.5	V
Forward Transconductance	gfs	V_{DS}=-10V, I_D=-2A	-	4	-	S
Dynamic and Switching Characteristics						
Total Gate Charge[2,3]	Q_g	V_{DS}=-20V, I_D=-1.5A, V_{GS}=-10V	-	3	-	nC
Gate-Source Charge[2,3]	Q_{gs}		-	0.2	-	
Gate-Drain Charge[2,3]	Q_{gd}		-	1.2	-	
Turn-On Delay Time[2,3]	$t_{d(on)}$	V_{DD}=-20V, R_G=6Ω, V_{GS}=-10V, I_D=-1.5A	-	2.9	-	nS
Rise Time[2,3]	t_r		-	8.4	-	
Turn-Off Delay Time[2,3]	$t_{d(off)}$		-	19.2	-	
Fall Time[2,3]	t_f		-	5.6	-	
Input Capacitance	C_{iss}	V_{DS}=-20V, V_{GS}=0V, F=1MHz	-	310	-	pF
Output Capacitance	C_{oss}		-	35	-	
Reverse Transfer Capacitance	C_{rss}		-	24	-	
Gate Resistance	R_g	V_{GS}=0V, V_{DS}=0V, F=1MHz	-	16	-	Ω
Source-Drain Ratings and Characteristics						
Continuous Source Current	I_S	V_G=V_D=0V, Force Current	-	-	-3.5	A
Pulsed Source Current	I_{SM}		-	-	-8	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=-1A, T_J=25°C	-	-	-1.2	V

Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Pulse test: pulse width ≦300us, duty cycle ≦2%.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

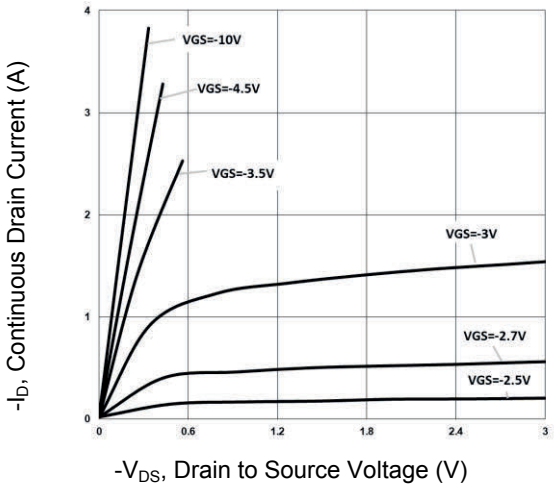


Figure 1. Typical Output Characteristics

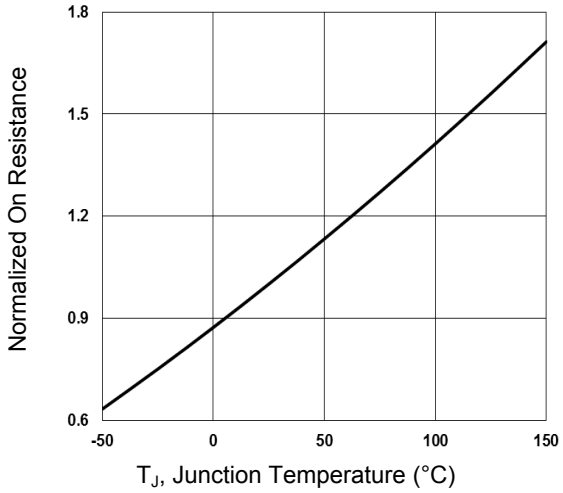


Figure 2. Normalized $R_{DS(ON)}$ vs. T_J

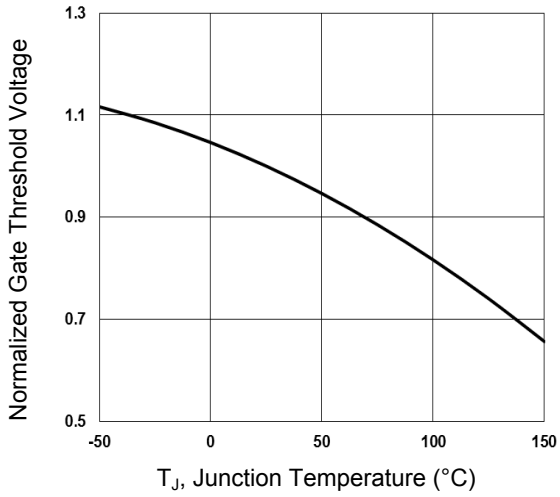


Figure 3. Normalized V_{th} vs. T_J

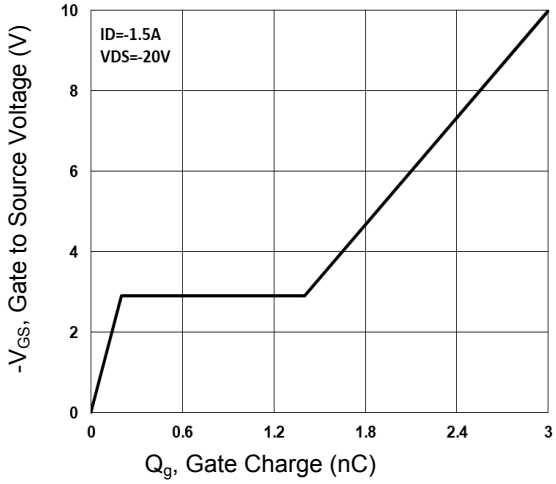


Figure 4. Gate Charge Characteristics

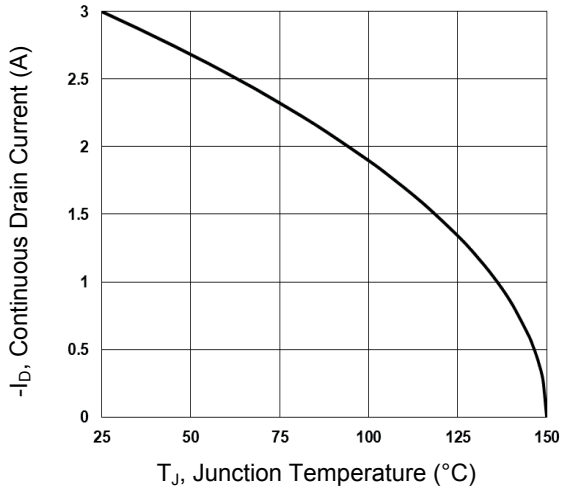


Figure 5. Continuous Drain Current vs. T_J

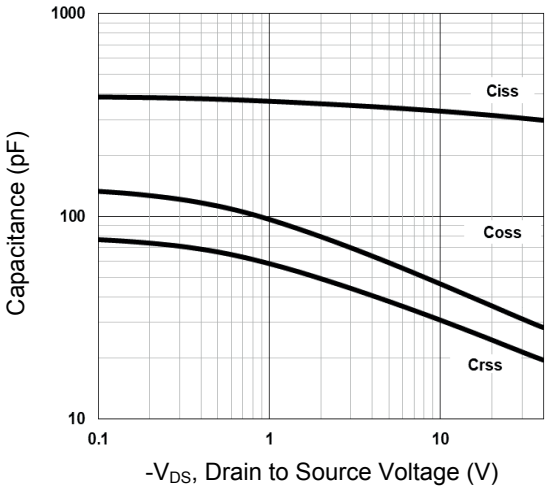


Figure 6. Capacitance Characteristics

Typical Electrical and Thermal Characteristic Curves

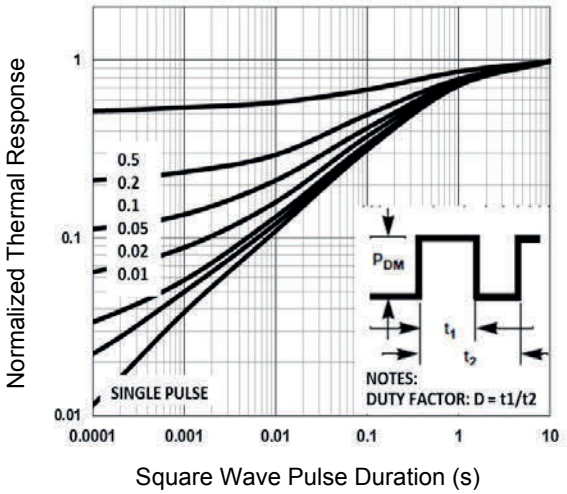


Figure 7. Normalized Transient Impedance

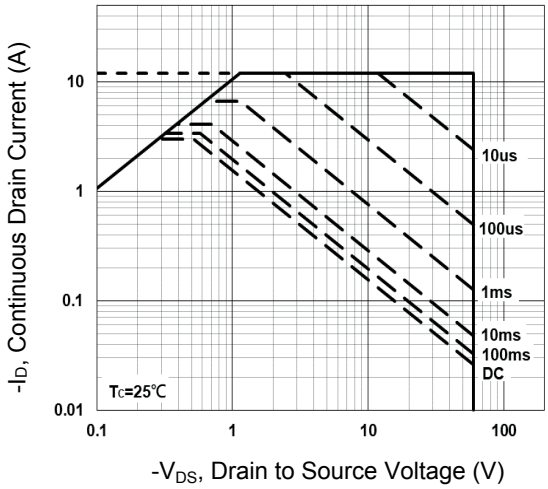
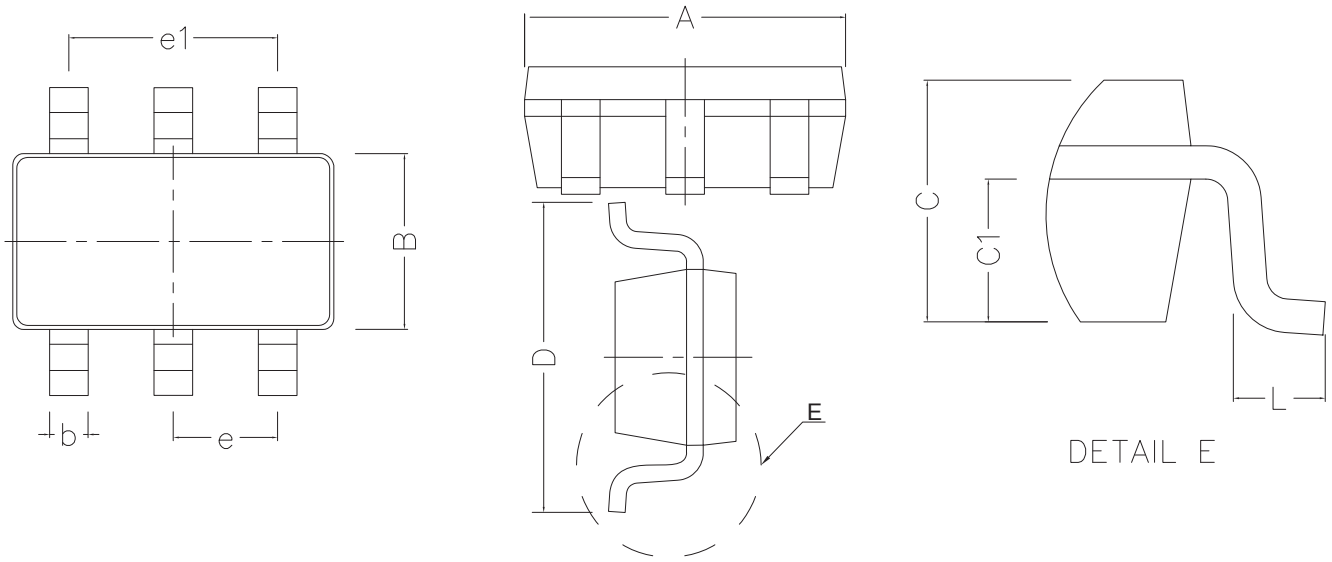


Figure 8. Maximum Safe Operation Area

Package Outline Dimensions (SOT-23-6L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.82	3.02	0.111	0.119
B	1.50	1.70	0.059	0.067
C	1.05	1.15	0.041	0.045
C1	0.60	0.70	0.024	0.028
D	2.65	2.95	0.104	0.116
L	0.30	0.60	0.012	0.024
b	0.28	0.42	0.011	0.017
e	0.95 TYP		0.037 TYP	
e1	1.90 TYP		0.075 TYP	

Order Information

Device	Package	Marking	Packaging	SPQ
GSFR4099	SOT-23-6L	R4099	Tape / Reel	3,000 pcs / Reel